In the Specification

The specification has been amended as follows:

Delete the paragraph beginning on page 3, line 25 and replace it with the following paragraph:

It is at this point in the screen printing process that distortion of the screening mask can occur because of the difference in cooling between the screening mask, which is relatively thin, and the mask frame which holds the screening mask, and which is relatively thick. In general, a screening mask is about 3 to 4 mils and a mask frame is about ⅛ inch thick. During the cooling the screening mask cools faster than the mask frame and the difference in cooling may cause a distortion of the screening mask and screening mask pattern.

Delete the paragraph beginning on page 11, line 12 and replace it with the following paragraph:

Fig. 4A is a schematic partial plan view of a portion of a screened substrate ~~screed~~ screened using a mask which has been cooled with the cooling plate of the invention after a heated cleaning step and showing via pattern features.

Delete the paragraph beginning on page 11, line 18 and replace it with the following paragraph:

Figs. 5A and 5B show a conventional cooling plate used to ~~a~~ cool a planar non-warped mask frame and the cooling plate in contact with the mask frame, respectively.

Delete the paragraph beginning on page 13, line 4 and replace it with the following paragraph:

The cleaned mask frame and screening mask are moved from the cleaning section to the cooling section in step 80. In step 90 the mask frame is positioned on supports so that the edges of the mask frame are supported but at least one middle portion of the mask frame is not supported. For example, only the opposed sides of the mask frame will be supported if continuous rails are used as shown in Figs. 3-3B.[[.]] If individual post supports are used at each corner of the mask frame then both the front and rear sides and opposed sides of the frame will be unsupported in the middle.

Delete the paragraph beginning on page 16, line 27 and replace it with the following paragraph:

In Fig. 8A the cooling plate 184 having a curved lower surface 186 is positioned above a mask frame 188 which is warped. However, when the cooling plate 184 is moved downward and in contact with the warped mask frame 188, the mask frame is bent further as shown in Fig. 8B and intimate contact is still made between the lower surface 186 of the cooling ~~plate184~~ plate 184 and the mask frame 188. Even in this case where a warped mask frame is being cooled, enhanced thermal efficiency is achieved.